

**FEE TRANSMITTAL**

Electronic Version v08

Stylesheet Version v08.0

**Title of  
Invention****SEMICONDUCTOR CHIP CAPABLE OF IMPLEMENTING WIRE BONDING  
OVER ACTIVE CIRCUITS**

Application Number :

Date :

First Named Applicant: Kun-Chih Wang

Attorney Docket Number: NAUP0559USA

**TOTAL FEE AUTHORIZED \$ 810**

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

**BASIC FILING FEE**

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	770	770
Subtotal For Basic Filing Fees: \$ 770			

**EXTRA CLAIM FEES**

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 16	0	1202	18	0
Independent Claims : 2	0	1201	86	0
Subtotal For Extra Claims Fees: \$ 0				

**ASSIGNMENT FEES**

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

**AUTHORIZED BILLING INFORMATION****The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:**

Deposit account number: 500801

Access Code \*\*\*\*

Deposit name: NORTH AMERICA INTERNATIONAL PATENT  
OFFICE

Deposit authorized name: WINSTON HSU

Signature: VAEB-JMXX-8IIL

Date (YYYYMMDD): 2004-02-09

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.